Secondary LDO Regulator Series for Local Power Supplies

1.5A Secondary LDO Regulators for Local Power Supplies

BA□□JC5 Series,BA00JC5W Series

No.09024EAT03

●Description

The BA□□JC5 are low-saturation regulators with an output current of 1.5 A and a voltage accuracy of ±1%. A broad output voltage range is offered, from 1.5V to 12V, and built-in overcurrent protection and thermal shutdown (TSD) circuits prevent damage due to short-circuiting and overloading, respectively.

●Features

1) Output current: 1.5A (min.)
2) Output voltage accuracy: ±1%
3) Broad output voltage range available: 1.5V -12V (BA□□JC5 series)
4) Low saturation-voltage type with PNP output
5) Built-in overcurrent protection circuit
6) Built-in thermal shutdown circuit
7) Integrated shutdown switch (BA□□JC5WT)
8) Operating temperature range: −40℃ to +105℃

●Applications

All electronic devices that use microcontrollers and logic circuits

●Product Lineup

Part Number	1.5	1.8	2.5	3.0	3.3	5.0	6.0	7.0	8.0	9.0	12.0	Variable	Package
BA□□JC5T	○	○	○	○	○	○	○	○	○	○	○	-	TO220FP-3
BA□□JC5WT	-	-	-	-	-	-	-	-	-	-	-	○	TO220FP-5 (V5)

Part Number: BA□□JC5□ □
a b c

Symbol	Description			
a	Output voltage specification			
	□□	Output voltage (V)	□□	Output voltage (V)
	15	1.5 V typ	60	6.0 V typ
	18	1.8 V typ	70	7.0 V typ
	25	2.5 V typ	80	8.0 V typ
	30	3.0 V typ	90	9.0 V typ
	33	3.3 V typ	J2	12.0 V typ
	50	5.0 V typ	00	Variable
b	Existence of switch	With W: A shutdown switch is provided. Without W: No shutdown switch is provided.		
c	Package T:	TO20FP-5, TO220FP-5･V5, TO220FP-3		

●Absolute Maximum Ratings (Ta = 25℃)

Parameter		Symbol	Limits	Unit
Power supply voltage		V_{CC}	18[*1]	V
Power dissipation	TO220FP-3	P_d	2000[*2]	mW
	TO220FP-5		2000[*2]	
	TO220FP-5·V5		2000[*2]	
Operating temperature range		T_{opr}	−40 to +105	℃
Ambient storage temperature		T_{stg}	−55 to +150	℃
Maximum junction temperature		T_{jmax}	150	℃

*1 Must not exceed Pd
*2 Derated at 16mW/℃ at Ta>25℃

●Recommended Operating Conditions

Parameter	Symbol	Min.	Max.	Unit
Input power supply voltage	V_{CC}[*3]	3.0	16.0	V
Input power supply voltage	V_{CC}[*4]	V_o + 1.0	16.0	V
Output current	I_o	-	1.5	A
Variable output voltage setting value	V_o	1.5	12	V

*3 When output voltage is 1.5 V, 1.8 V, or 2.5 V.
*4 When output voltage is 3.0 V or higher.

●Electrical Characteristics

BA□□JC5T(Unless otherwise specified, Ta = 25℃; Vcc = V_{CCDC}[*5])

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Output voltage	Vo	Vo (T) × 0.99	Vo (T)	Vo (T) × 1.01	V	Io = 200 mA
Minimum I/O voltage difference[*6]	ΔVd	-	0.3	0.5	V	Io = 200 mA, Vcc = 0.95 × Vo
Output current capacity	Io	1.5	-	-	A	
Input stability[*7]	Reg.I	-	5	60	mV	Vcc = Vo + 1.0 V→16 V, Io = 200 mA
Load stability	Reg.L	-	5	60	mV	Io = 5 mA→1.5 A
Temperature coefficient of output voltage[*8]	Tcvo	-	±0.02	-	%/℃	Io = 5 mA, Tj = 0℃ to 125℃

Vo (T): Set output voltage
*5 Vo = 1.5 V, 1.8 V, 2.5 V : Vcc = 3.3 V, Vo = 3.0 V, 3.3 V : Vcc = 5 V,
Vo = 5.0 V : Vcc : 8 V, Vo = 6.0 V, 6.3 V : Vcc = 9.0 V, Vo = 8.0 V : Vcc = 11 V,
Vo = 9.0 V : Vcc = 12 V, Vo = 12 V : Vcc = 15 V
*6 Vo ≥ 3.3 V
*7 Change Vcc from 3.0 V to 16 V if 1.5 V ≤ Vo ≤ 2.5 V.
*8 Operation guaranteed

BA00JC5WT (−V5)(Unless otherwise specified, Ta = 25℃, Vcc = 3.3 V, V_{CTL} = 3 V, R1 = 30 kΩ, R2 = 30 kΩ[*9])

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Reference voltage	Vo	1.2375	1.250	1.2625	V	Io = 50 mA
Shutdown circuit current	Isd	-	0	10	μA	V_{CTL} = 0 V while in OFF mode
Minimum I/O voltage difference	ΔVd	-	0.3	0.5	V	Io = 500 mA, Vcc = 2.5 V
Output current capacity	Io	1.5	-	-	A	
Input stability	Reg.I	-	5	60	mV	Vcc = 4.5 V→16 V, Io = 200 mA
Load stability	Reg.L	-	5	60	mV	Io = 5 mA →1.5 A
Temperature coefficient of output voltage[*10]	Tcvo	-	±0.02	-	%/℃	Io = 5 mA, Tj = 0℃ to 125℃

*9 VOUT = Vc × (R1 + R2) / R1 (V)
*10 Design guarantee (No total shipment inspection is made.)

●**Electrical Characteristics Curves** (Unless otherwise specified, Ta = 25℃; Vcc = 8 V; V_{CTL} = 3 V; I_O = 0 mA)

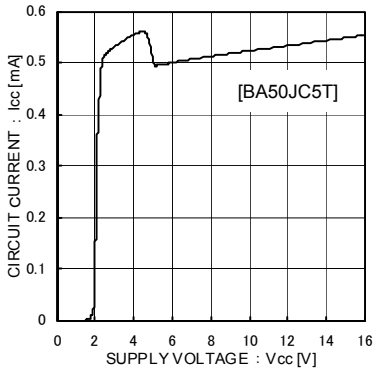


Fig.1 Circuit Current

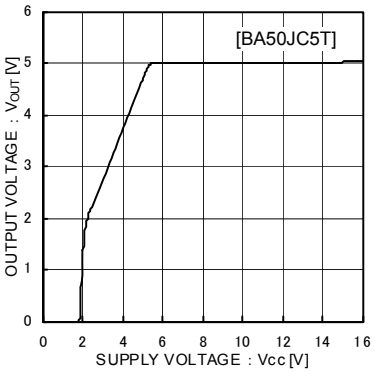
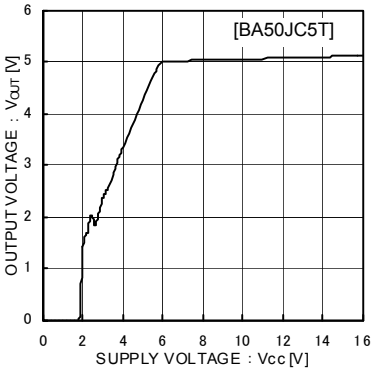


Fig.2 Input Stability(Io=0mA)



.3 Input Stability
(Io = 1.5 A)

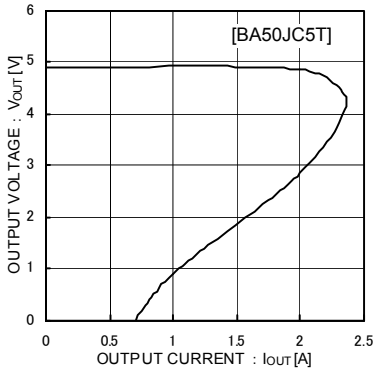


Fig.4 Load Stability

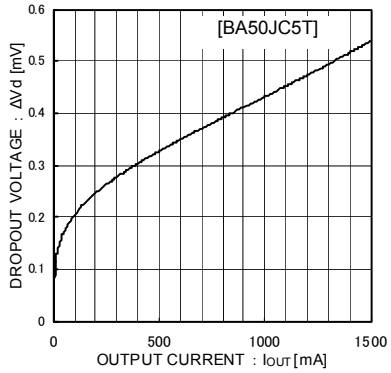


Fig.5 I/O Voltage Difference

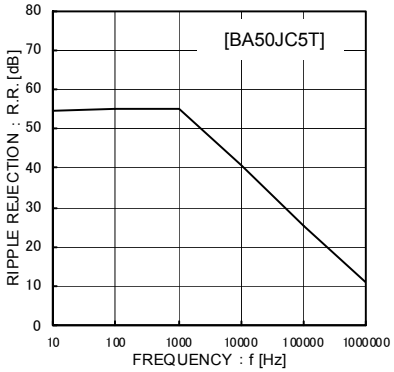


Fig.6 Ripple Rejection

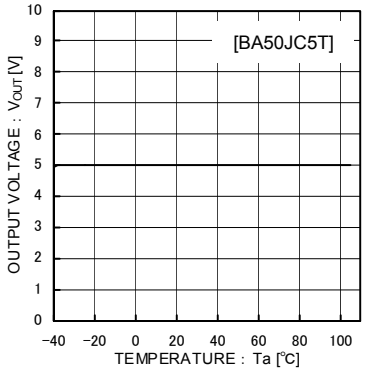


Fig.7 Output Voltage vs Temperature

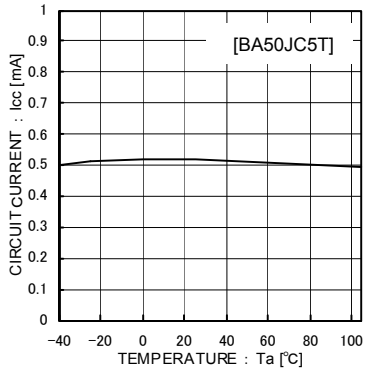


Fig.8 Circuit Current Temperature

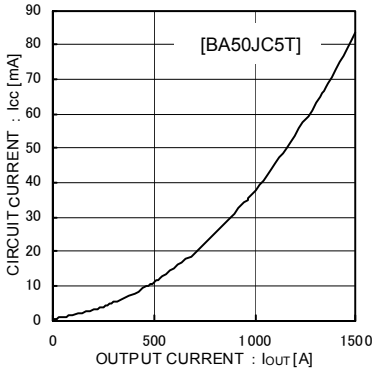


Fig.9 Circuit Current Classified by Load

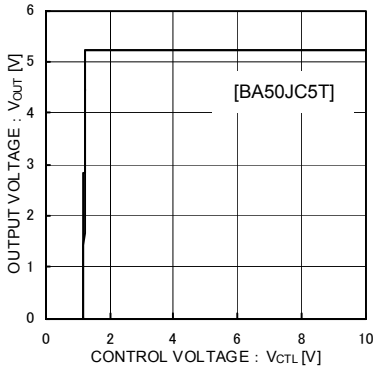


Fig.10 CTL Voltage vs Output Voltage

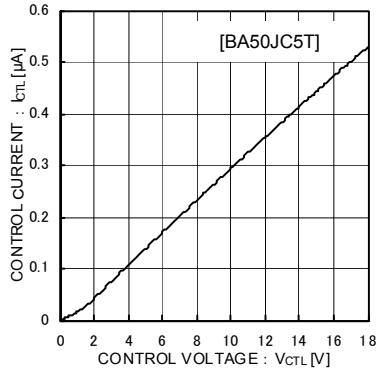


Fig.11 CTL Voltage vs CTL Current

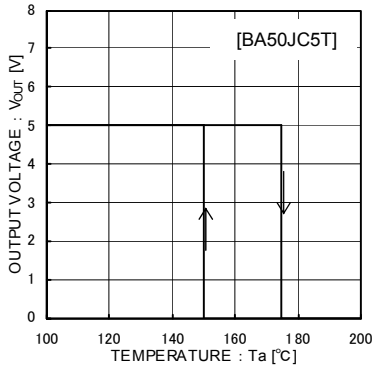
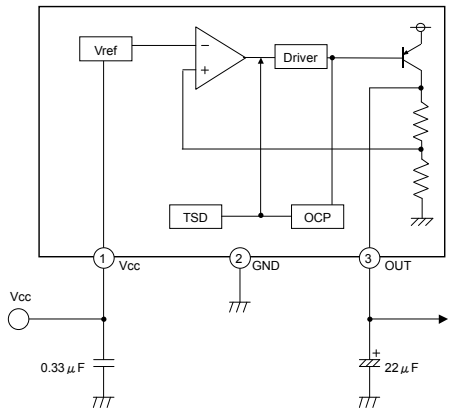


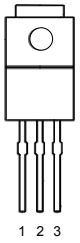
Fig.12 Thermal Shutdown Circuit
(Io = 5 mA)

● **Block Diagrams / Standard Example Application Circuits**

[BA□□JC5T]



TOP VW



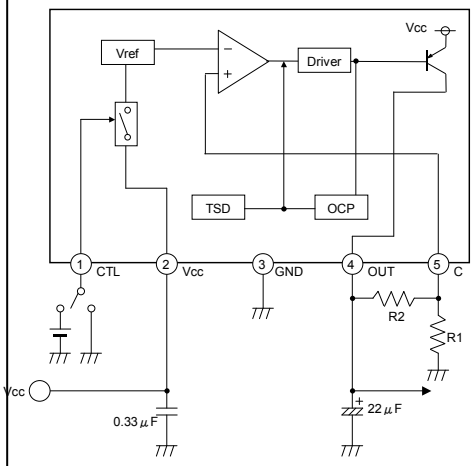
TO220FP-3

Pin No.	Pin name	Function
1	Vcc	Power supply voltage input
2	GND	GND
3	OUT	Voltage output

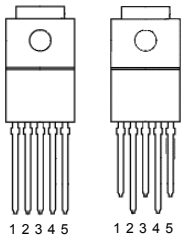
PIN	External capacit setting range
Vcc (1 Pin)	Approximately 0.33 μF
OUT (3 Pin)	22 μF to 1000 μF

Fig.13

[BA00JC5WT]



TOP VIEW



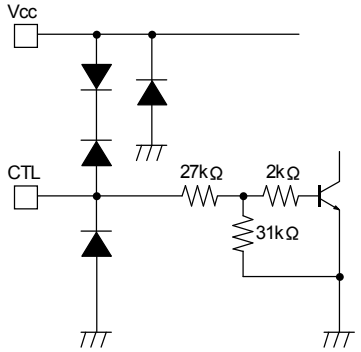
TO220FP-5 TO220FP-5 (V5)

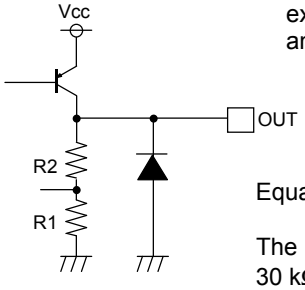
Pin No.	Pin name	Function
1	CTL	Output voltage on/off control
2	Vcc	Power supply voltage input
3	GND	GND
4	OUT	Voltage output
5	C	ADJ pin

PIN	External capacit setting range
Vcc (2 Pin)	Approximately 0.33 μF
OUT (4 Pin)	22 μF to 1000 μF

Fig.14

● **Input / Output Equivalent Circuits**





* For the BA00JC5WT, connect R1 and R2 externally between the ADJ and GND pins and between the OUT and ADJ pins.

Equation: VOUT = Vc × (R1 + R2) / R1
(Vc = 1.25 V (Typ.))
The recommended R1 value is approximately 30 kΩ to 150 kΩ.

Fig.15

●Thermal Derating Curve

• TO220FP-3/TO220FP-5/TO220FP-5 (V5)

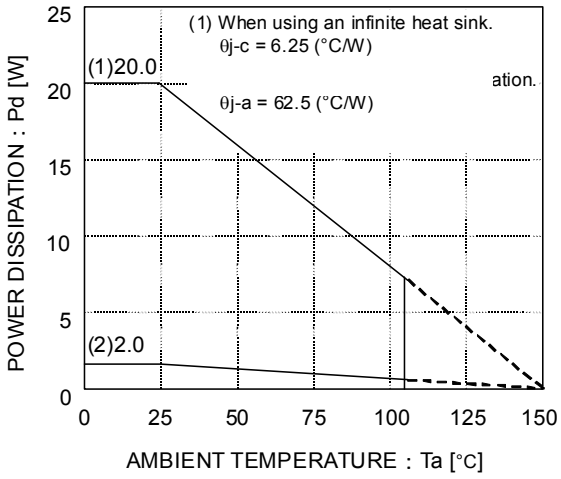


Fig.17

The characteristics of the IC are greatly influenced by the operating temperature. If the temperature exceeds the maximum junction temperature T_{jmax}, deterioration or damage may occur. Implement proper thermal designs to ensure that power dissipation is within the permissible range in order to prevent instantaneous damage resulting from heat and maintain the reliability of the IC for long-term operation.

The following method is used to calculate the power consumption Pc (W):

$Pc = (Vcc - Vo) \times Io + Vcc \times Icca$

Power dissipation $Pd \geq Pc$

Vcc : Input voltage
Vo : Output current
Io : Load current
Icca : Circuit current

The load current Io is calculated:

$$Io \leq \frac{Pd - Vcc \times Icca}{Vcc - Vo}$$

Calculation Example:

Vcc = 6.0V and Vo = 5.0V at Ta = 85℃

$$\frac{1.040 - 6.0 \times Icca}{6.0 - 5.0}$$

$\theta ja = 62.5°C/W \rightarrow -16.0mW/°C$

$25°C = 2000mW \rightarrow 85°C = 1040mW$

Io ≤ 860mA (Icca ≈ 30mA)

Refer to the above and implement proper thermal designs so that the IC will not be used under excessive power dissipation conditions under the entire operating temperature range.

The power consumption Pc of the IC in the event of shorting (i.e. the Vo and GND pins are shorted) can be obtained from the following equation: Pc = Vcc × (Icca + Ishort) (Ishort: short current)

●Operation Notes

- Vcc pin

  Insert a capacitor (0.33 μF approx.) between VCC and GND.
  The capacitance will vary depending on the application. Use a suitable capacitance and implement designs with sufficient margins.

- GND pin

  Verify that there is no potential difference between the ground of the application board and the IC.
  If there is a potential difference, the set voltage will not be output accurately, resulting in unstable IC operation.
  Therefore, lower the impedance by designing the ground pattern as wide and as short as possible.

- CTL pin

  The CTL pin turns on at an operating power supply voltage of 2.0 V or higher and turns off at 0.8 V or lower.
  There is no particular order when turning the power supply and CTL pins on or off.

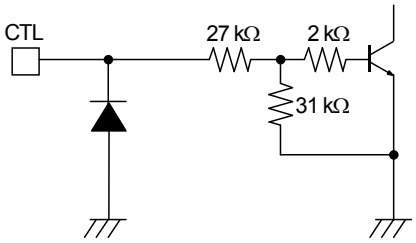


Fig.18 Input Equivalent Circuit

●Vo pin

Insert a capacitor between the Vo and GND pins in order to prevent output oscillation.

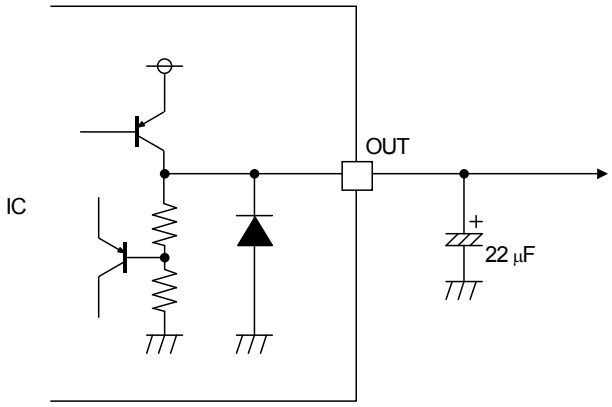


Fig.19 Output Equivalent Circuit

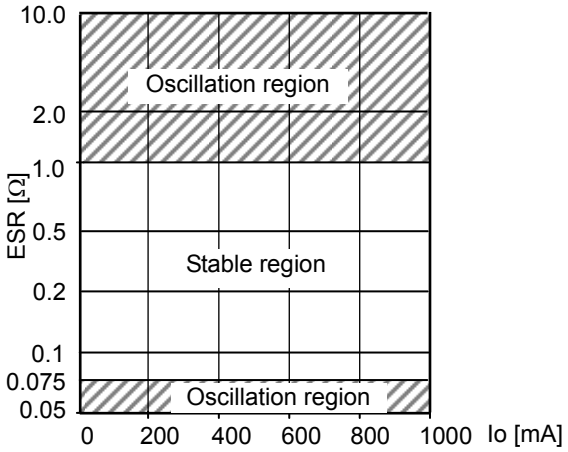


Fig. 20 IO vs ESR

The capacitance may vary greatly with temperature changes, thus making it impossible to completely prevent oscillation. Therefore, use a tantalum aluminum electrolytic capacitor with a low ESR (Equivalent Serial Resistance). The output will oscillate if the ESR is too high or too low, so refer to the ESR characteristics in Fig. 20 and operate the IC within the stable region. Use a capacitor within a capacitance between 22μF and 1,000μF.

●Precautions

1. Absolute maximum ratings
   An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.
2. GND voltage
   The potential of GND pin must be minimum potential in all operating conditions.
3. Thermal design
   Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions.
4. Inter-pin shorts and mounting errors
   Use caution when positioning the IC for mounting on printed circuit boards. The IC may be damaged if there is any connection error or if pins are shorted together.
5. Actions in strong electromagnetic field
   Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.
6. Testing on application boards
   When testing the IC on an application board, connecting a capacitor to a pin with low impedance subjects the IC to stress. Always discharge capacitors after each process or step. Always turn the IC's power supply off before connecting it to or removing it from a jig or fixture during the inspection process. Ground the IC during assembly steps as an antistatic measure. Use similar precaution when transporting or storing the IC.
7. Regarding input pin of the IC
   This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of these P layers with the N layers of other elements, creating a parasitic diode or transistor. For example, the relation between each potential is as follows:
   When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode.
   When GND > Pin B, the P-N junction operates as a parasitic transistor.
   Parasitic diodes can occur inevitable in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Accordingly, methods by which parasitic diodes operate, such as applying a voltage that is lower than the GND (P substrate) voltage to an input pin, should
8. Ground Wiring Pattern
   When using both small signal and large current GND patterns, it is recommended to isolate the two ground patterns, placing a single ground point at the ground potential of application so that the pattern wiring resistance and voltage variations caused by large currents do not cause variations in the small signal ground voltage. Be careful not to change the GND wiring pattern of any external components, either.
9. Thermal shutdown circuit
   The IC incorporates a built-in thermal shutdown circuit (TSD circuit). The thermal shutdown circuit (TSD circuit) is designed only to shut the IC off to prevent thermal runaway. It is not designed to protect the IC or guarantee its operation. Do not continue to use the IC after operating this circuit or use the IC in an environment where the operation of this circuit is assumed.
10. Overcurrent Protection Circuit
    An overcurrent protection circuit is incorporated in order to prevention destruction due to short-time overload currents. Continued use of the protection circuits should be avoided. Please note that the current increases negatively impact the temperature.
11. Damage to the internal circuit or element may occur when the polarity of the Vcc pin is opposite to that of the other pins in applications. (I.e. Vcc is shorted with the GND pin while an external capacitor is charged.) Use a maximum capacitance of 1000μF for the output pins. Inserting a diode to prevent back-current flow in series with Vcc or bypass diodes between Vcc and each pin is recommended.

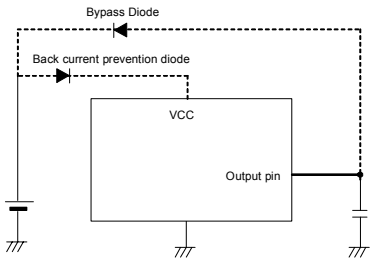


Fig. 21 Bypass Diode

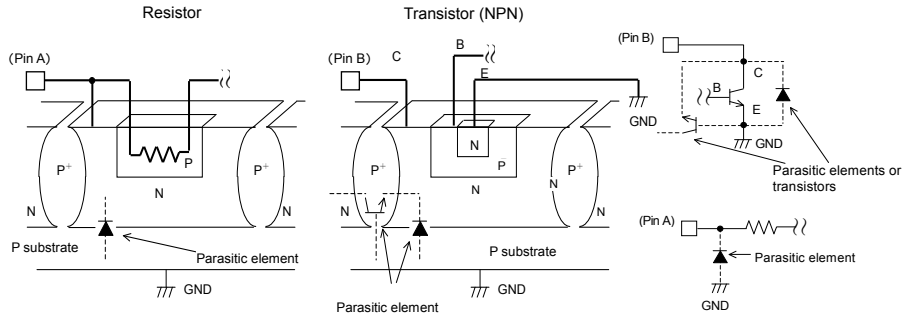
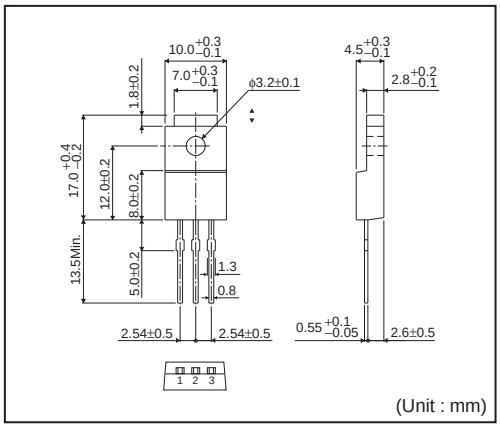


Fig. 22 Example of Simple Bipolar IC Architecture

●Ordering part number

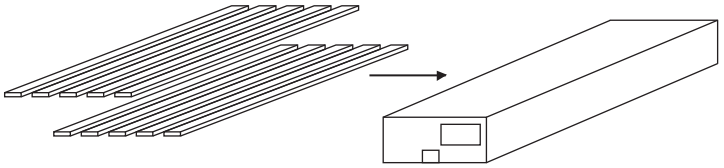
B A	0 0	J C 5	W	T	-		
Part number	Output voltage 00:Variable Other:Fixed	Current capacity 1.5A	Shutdown switch W : Include	Package T : TO220FP-3 TO220FP-5 TO220FP-5(V5)		Packaging and forming specification None:Tube Contener	

TO220FP-3



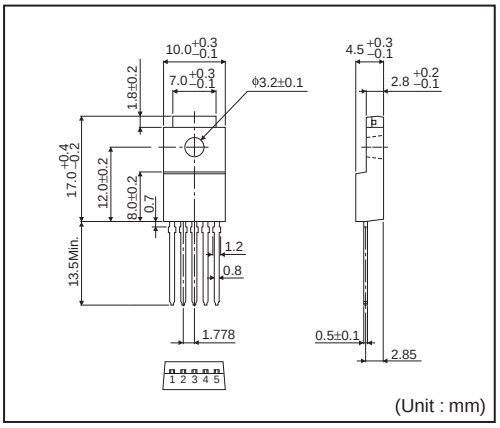
<Tape and Reel information>

Container	Tube
Quantity	500pcs
Direction of feed	Direction of products is fixed in a container tube



∗Order quantity needs to be multiple of the minimum quantity.

TO220FP-5



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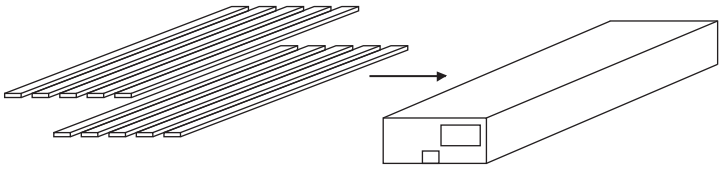
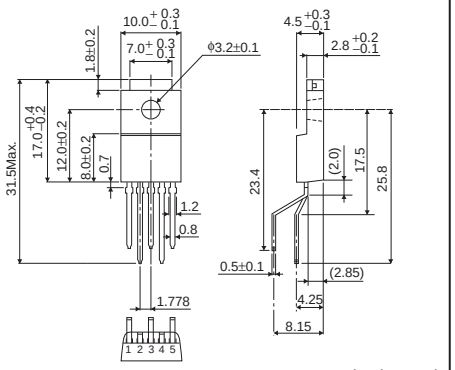


∗Order quantity needs to be multiple of the minimum quantity.

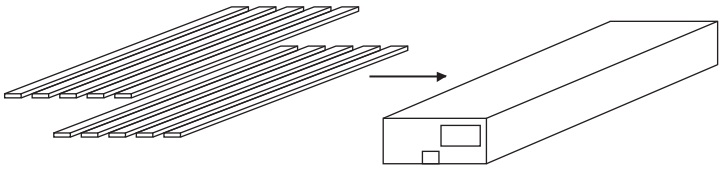
TO220FP-5(V5)



(Unit : mm)

<Tape and Reel information>

Container	Tube
Quantity	500pcs
Direction of feed	Direction of products is fixed in a container tube



∗Order quantity needs to be multiple of the minimum quantity.

Notes

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